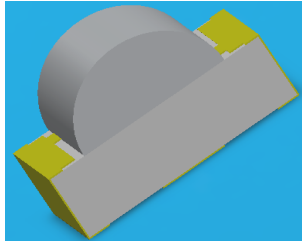


Chip Infrared LED With spherical top view Lens LKIR30102C-A01(XY)



Preliminary

This is a preliminary specification intended for design purposes and subject to change without prior notice.

Features

- Small double-end package
- Low forward voltage
- Good spectral matching to Si photo detector
- Pb free
- The product itself will remain within RoHS compliant version
- Compliance with EU REACH
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Descriptions

- LKIR30102C-A01 is an infrared emitting diode in miniature SMD package which is molded in a water clear epoxy with spherical top view lens.
- The device is spectrally matched with silicon photodiode and phototransistor

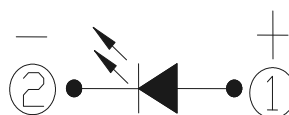
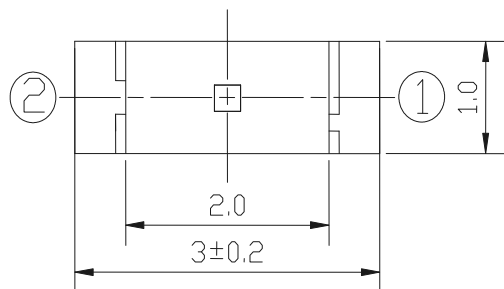
Applications

- PCB mounted infrared sensor
- Infrared emitting for miniature light barrier
- Floppy disk drive
- Optoelectronic switch
- Smoke detector

Device Selection Guide

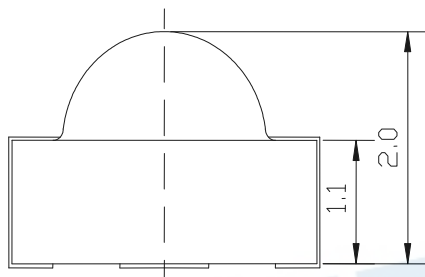
Part Category	Chip Material	Lens Color
IR	GaAlAs	Water Clear

Package Dimensions

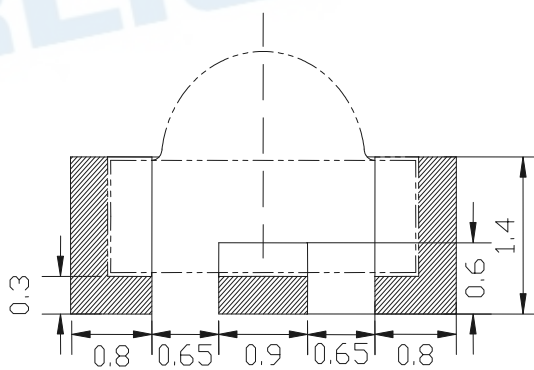
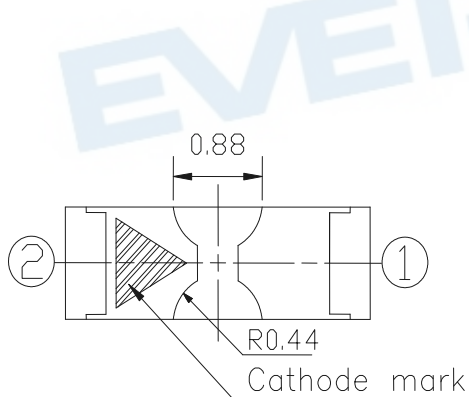


Polarity

- ① Anode
- ② Cathode



For reflow soldering(propose)



- Notes:**
- 1.All dimensions are in millimeters
 - 2.Tolerances unless dimensions ± 0.1 mm
 - 3.Suggested pad dimension is just for reference only
Please modify the pad dimension based on individual need

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Units
Continuous Forward Current	I _F	65	mA
Reverse Voltage	V _R	5	V
Operating Temperature	T _{opr}	-25 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +85	°C
Soldering Temperature*1	T _{sol}	260	°C
Power Dissipation at (or below) 25°C Free Air Temperature	P _d	130	mW

Notes: *1: Soldering time ≤ 5 seconds

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Condition	Min.	Typ.	Max.	Units
Radiant Intensity	I _e	I _F =20mA	0.5	0.8	--	mW/sr
Peak Wavelength	λ _p		--	940	--	nm
Spectral Bandwidth	Δλ		--	45	--	nm
Forward Voltage	V _F		--	1.2	1.5	V
View Angle	2θ _{1/2}		--	160	--	deg
Reverse Current	I _R	V _R =5V	--	--	10	μA

Typical Electro-Optical Characteristics Curves

Fig.1 Forward Current vs. Ambient Temperature

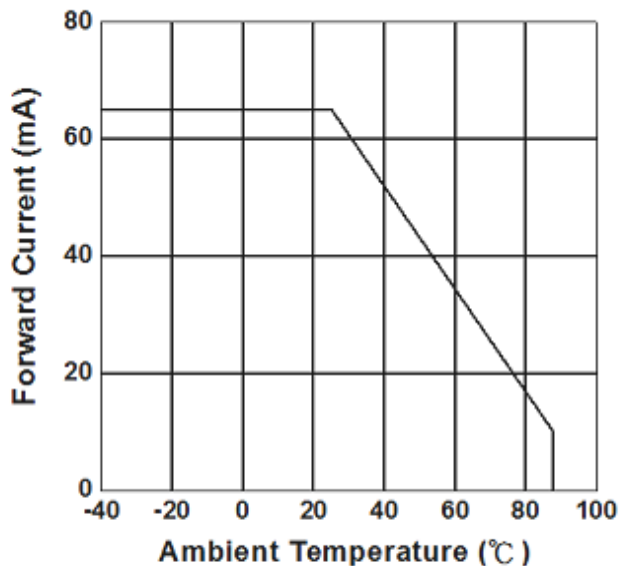


Fig.2 Spectral Distribution

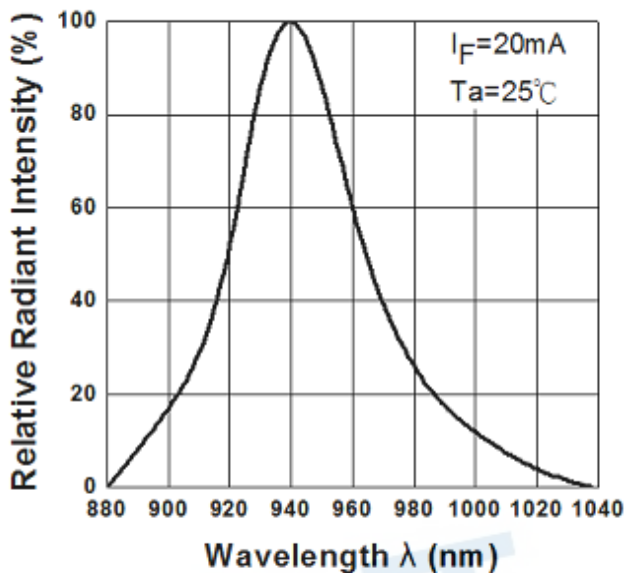


Fig.3 Forward Current vs. Forward Voltage

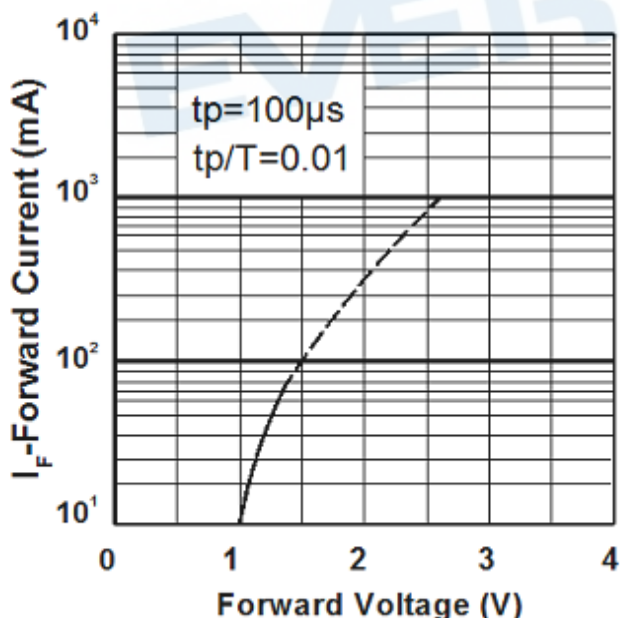
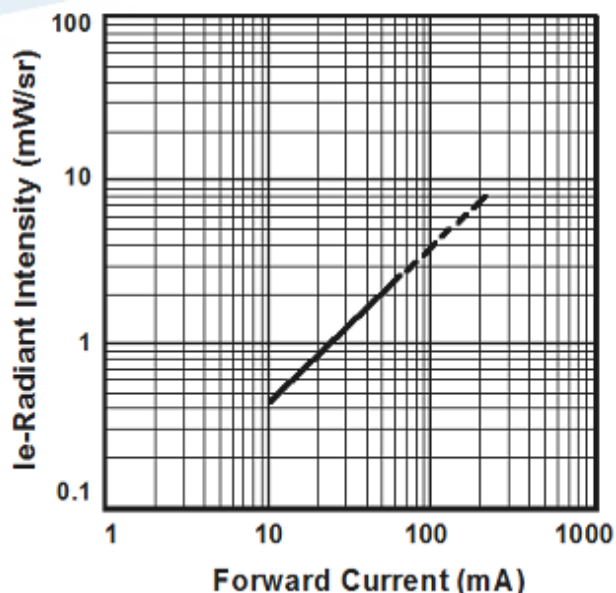
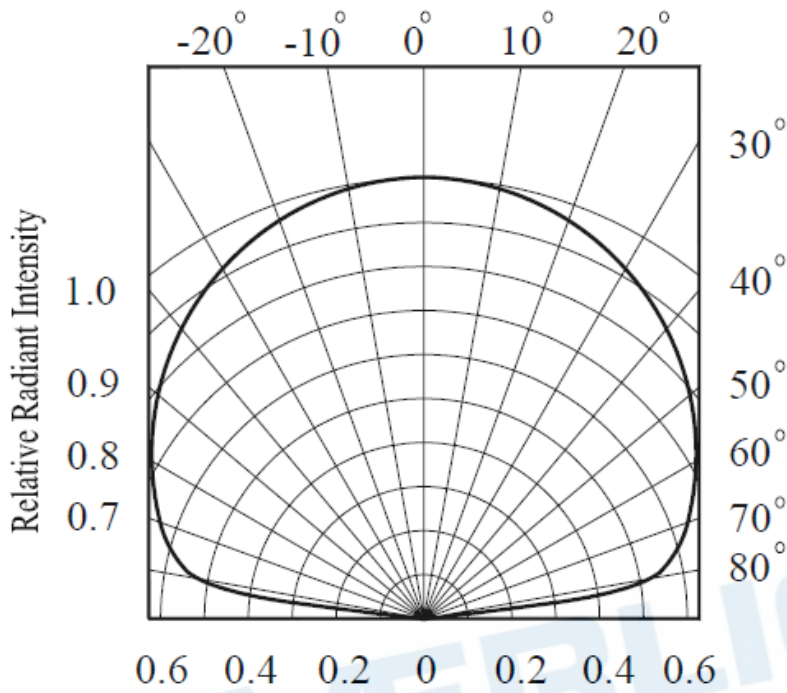


Fig.4 Radiant Intensity vs. Forward Current



Typical Electro-Optical Characteristics Curves

Fig.5 Relative Radiant Intensity vs. Angular Displacement



Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package, the LEDs should be kept at 10°C~30°C and 90%RH or less.

2.3 The LEDs suggested be used within one year.

2.4 After opening the package, the devices must be stored at 10°C ~30°C and ≤ 60%RH, and used within 168 hours (floor life). If unused LEDs remain, it should be stored in moisture proof packages.

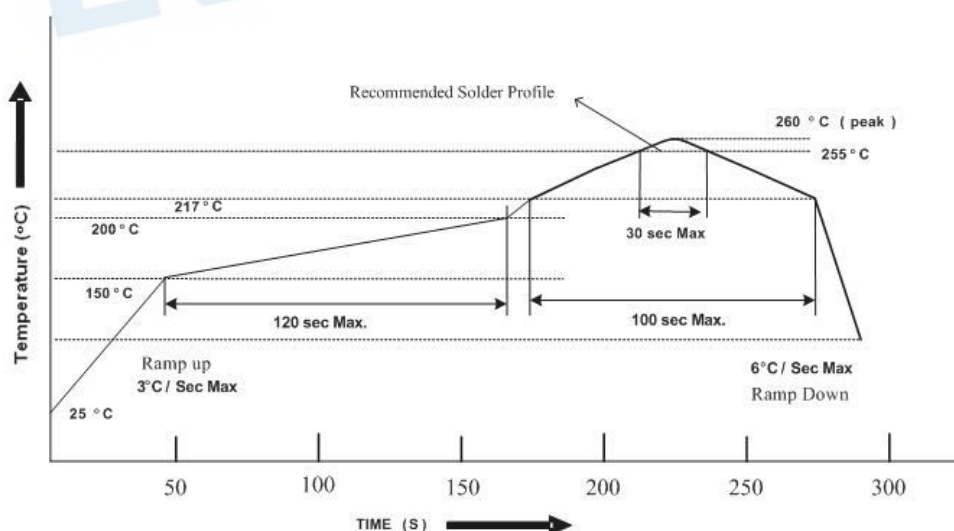
2.5 If the moisture absorbent material (desiccant material) has faded or unopened bag has exceeded the shelf life or devices (out of bag) have exceeded the floor life, baking treatment is required.

2.6 If baking is required, refer to IPC/JEDEC J-STD-033 for bake procedure or recommend the following conditions:

96 hours at 60°C ± 5°C and < 5 % RH (reeled/tubed/loose units).

3. Soldering Condition

3.1 Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times

3.3 When soldering, do not put stress on the LEDs during heating

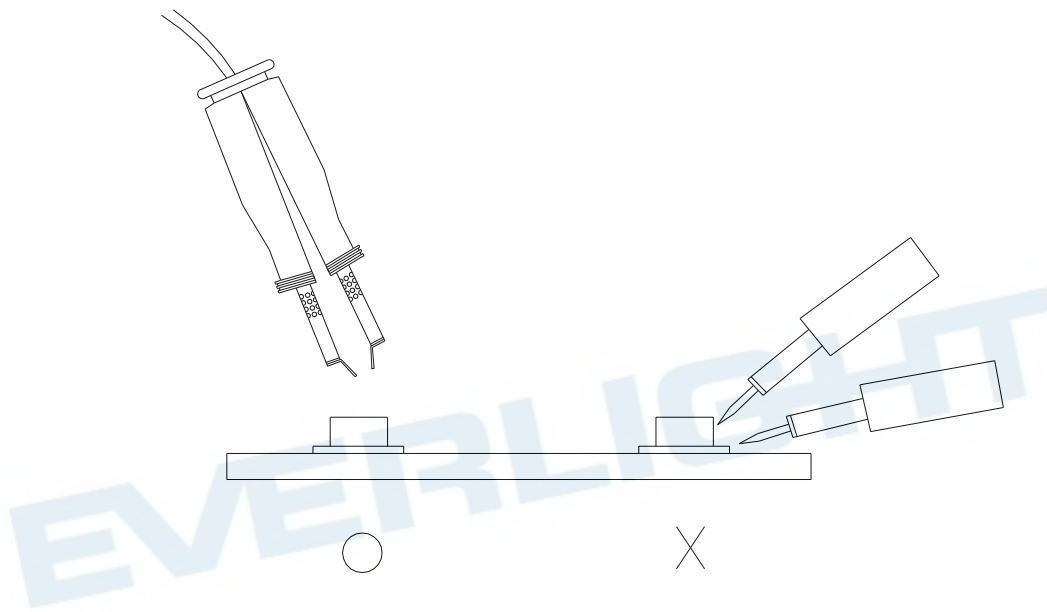
3.4 After soldering, do not warp the circuit board

4. Soldering Iron

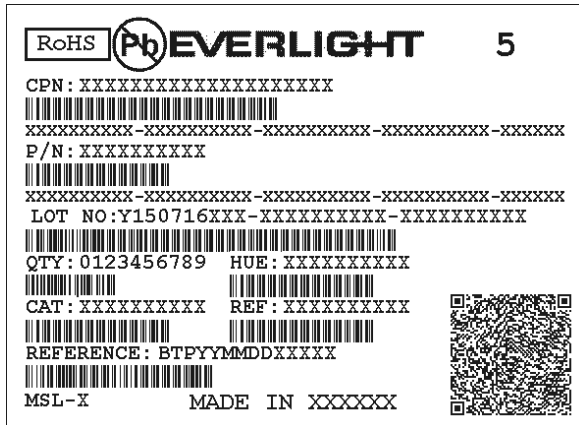
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



Label Form Specification



CPN: Customer's Production Number

P/N : Production Number

LOT No: Lot Number

QTY: Packing Quantity

HUE: Peak Wavelength

CAT: Ranks

REF: Reference

MSL-X: MSL Level

Made In: Manufacture place

DISCLAIMER

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3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
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